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5 a turntable having a polishing surface thereon;

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10      a pressurized fluid source for supplying pressurized
      fluid;
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2. An apparatus according to claim 1, wherein said  
20 plurality of areas comprises concentric annular areas.

4. An apparatus according to claim 1, wherein said first pressing force and a pressure of said pressurized fluid

are variable independently of each other.

5. An apparatus according to claim 1, wherein a pressure of said pressurized fluid is variable in each of said  
5 areas.

6. An apparatus according to claim 1, further comprising:

a presser ring vertically movably disposed around  
10 said top ring; and

a pressing device for pressing said presser ring against said polishing surface under a second pressing force which is variable.

7. An apparatus according to claim 1, wherein said  
15 top ring has a recess defined therein for accommodating the workpiece therein.

8. A method of polishing a workpiece, comprising the  
20 steps of:

holding a workpiece between a polishing surface of a turntable and a holding surface of a top ring disposed above said turntable;

pressing the workpiece by said top ring against said  
25 polishing surface under a first pressing force; and

ejecting pressurized fluid from openings in a plurality of areas in said holding surface of said top ring toward the workpiece held by said top ring, said pressurized

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fluid being selectively ejectable from said openings in said respective areas; and

polishing the workpiece in such a state that a pressing force applied to the workpiece by said pressurized fluid is variable in a central portion and an outer circumferential portion of the workpiece, respectively.

9. A method according to claim 8, further comprising the step of:

10 pressing a presser ring vertically movably disposed around said top ring against said polishing surface around the workpiece under a second pressing force which is determined based on said first pressing force.

15 10. A method according to claim 8, said second pressing force is determined on the basis of a pressure distribution on the workpiece caused by said pressurized fluid ejected from said openings in said respective areas.

20 11. A top ring for supporting the workpiece to be polished, for use in a polishing apparatus, comprising:

a holding surface for holding the workpiece; and

a plurality of openings, provided in said holding surface, from which pressurized fluid is ejected, a plurality of areas each having said openings being defined in said holding surface so that said pressurized fluid is selectively ejectable from said openings in said respective areas.